

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
EFFECTIVE DATE:	02/07/2007

CONVEYING PARTY DATA

Name	Execution Date
Hsiao-Tzu Lu	02/07/2007
Hung Chang Hsieh	02/07/2007
Kuci Shun Chen	02/07/2007
Hsueh-Hung Fu	02/15/2007
Ching-Hua Hsieh	02/15/2007
Shau-Lin Shue	02/07/2007

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11686142

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	24061.831
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CH \$40.00 11686142

PATENT

NAME OF SUBMITTER:

David M. O'Dell

Total Attachments: 3

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ASSIGNMENT

WHEREAS, we,

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|-----|------------------|----|---|
| (1) | Hsiao-Tzu Lu | of | No. 11, 132 Alley, Chai-Chiao Rd.
Hsinchu 300, Taiwan, R.O.C. |
| (2) | Hung Chang Hsieh | of | 9F, No. 72-12, Lane 531, Sec. 1, Kung-Fu Rd.
Hsin-Chu City, Taiwan, R.O.C. |
| (3) | Kuei Shun Chen | of | 5F, 22 634 LN Nan-Da Rd.
Hsin-Chu 300, Taiwan, R.O.C. |
| (4) | Hsueh-Hung Fu | of | 4F, No. 22, Alley 6, Lane 485, Sec. 1, Kuan-Fu Rd.
Hsinchu, Taiwan, R.O.C., |
| (5) | Ching-Hua Hsieh | of | 3Fl., No. 16, Alley 7, Lane 384, Sec. 1, Junghua Rd.
Hsinchu 300, Taiwan, R.O.C. |
| (6) | Shau-Lin Shue | of | 5F, No. 25, Alley 6, Lane 485, Kwung-Fu Rd. I
Hsinchu, Taiwan, R.O.C. |

have invented certain improvements in

METHODS AND SYSTEMS FOR LITHOGRAPHY ALIGNMENT

for which we have executed an application for Letters Patent of the United States of America,

filed on 3/14/07 and assigned application number 11/686,142, and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past

damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Hsiao-Tzu Lu

Residence Address: No. 11, 132 Alley, Chai-Chiao Rd.
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Dated: 2007. 2/7

Hsiao Tzu Lu
Inventor Signature

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Dated: 2007. 2. 7

Hung - Chang Hsieh
Inventor Signature

Inventor Name: Kuci Shun Chen

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Dated: 02/07/2007

Kuci Shun Chen
Inventor Signature

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Dated: 2/15/07

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Inventor Signature

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Dated: 2/15/07

Ching-Hua Hsieh
Inventor Signature

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Dated: 02/07/2007

Shau-Lin Shue
Inventor Signature